

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	10/753914	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 11:07
S2	1	09/948877	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 11:07
S3	1736	"KONINKLIJKE PHILIPS" as	USPAT	OR	ON	2003/08/19 13:35
S4	1	10/788990	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 09:57
S5	2611726	tape (flexible elast\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 09:58
S6	2980350	substrate carrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 09:58
S7	37557	S5 adj; S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:04
S8	2007	mold adj gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:04
S9	64571	runner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:04
S10	33	S8 near4 "7"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:05

S11	168	S8 near4 S9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:05
S12	8	S7 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:06
S13	8	S12 and S8 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:09
S14	168	S8 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:10
S15	8	S7 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:10
S16	19	S8 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:21
S17	7483981	(open\$5 via hole aperture)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:23
S18	343380	(((printed adj circuit PC wiring) adj (board card module)) pcb PWB motherboard mother adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:23
S19	3214575	S6 S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:24
S20	4	"5981873" pn. "6329606" pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:37

S21	3	S20 and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:30
S22	49475	S5 adj S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:32
S23	25094	mold adj S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:33
S24	9353929	S17 near8 S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:34
S25	385819	S17 near8 S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:37
S26	18	S25 near9 S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:43
S27	2	S26 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:37
S28	1	S21 and S19 and S17 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:44
S29	18	S26 and S19 and S17 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 10:56
S30	1	10/704514	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 11:01

S31	1	10/762380	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:40
S32	1109607	mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:40
S33	3111415	inlet passage channel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:40
S34	2849	S32 adj S33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:41
S35	4943064	metal\$6 trace conducti\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:42
S36	5469171	metal\$6 trace conduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:42
S37	4819	S34 S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:43
S38	7117415	S6 4with S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:43
S39	677	S37 with S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 12:45
S40	4	S39 same S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:02

S41	5938	S25 same S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:03
S42	4908	S25 with S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:04
S43	3139986	(encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:04
S44	5167460	tool apparatus die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:04
S45	67068	S43 near S44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:42
S46	6	S42 same S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:10
S47	150	S42 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:06
S48	385	S42 with S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:10
S49	41	S48 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:41
S50	615087	tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:41

S51	51763	S43 adj S44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:48
S52	393	S50 near9 S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:49
S53	2164995	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:50
S54	31499	S50 near9 S53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:50
S55	375	S51 same S54	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:51
S56	308	S51 with S54	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:53
S57	22382	S51.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 13:53
S58	102	S56 and S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:09
S59	64571	runner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:09
S60	12831	S43 near9 S59	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:10

S61	4	S58 and S60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:16
S62	942704	gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:16
S63	3040	S43 adj S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:18
S64	646314	S50 S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:18
S65	72	S64 same S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:32
S66	72	S65 and S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 14:32
S67	6	("5391923").URPN.	USPAT	OR	ON	2005/06/10 14:44
S68	5	("2054609" "4648481" "5064706" "5196917").PN	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:52
S69	1537916	runner path	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:52
S70	648619	running	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:52
S71	1960301	S69 S70	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:54
S72	13700	S43 near3 S71	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:55
S73	38269	S64 near8 S17	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:56

S74	1940	S71 with S73	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 15:01
S75	32581	S36 near8 S64	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:59
S76	124	S74 same S75	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 14:59
S77	14	S72 with S73	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 15:02
S78	46	S72 same S73	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 15:01
S79	265	S72 and S73	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 15:01
S80	91	S79 and S75	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 16:13
S81	45627	wir\$4 near bond\$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 16:13
S82	55	S80 and S81	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 16:14
S83	10	S77 and S81	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 16:14
S84	278990	tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:39
S85	17859	S37 S72	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:40
S86	884232	S64 S84	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:40
S87	126	S85 near6 S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:47

S88	36	S87 and S81	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:40
S89	4054088	support\$4 stiffener	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 16:48
S90	92	S87 and S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:06
S91	976	S85 with S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:06
S92	492	S85 same S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:07
S93	26	S91 same S92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:15
S94	289818	S89 near6 S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:16
S95	3	S92 same S94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:18
S96	58	S92 and S94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:38
S97	1109607	mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:16

S98	15706	upper adj S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 17:40
S99	133	S91 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 18:19
S10 0	1547	S85 near6 S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 18:20
S10 1	455	S37 near6 S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 18:21
S10 2	10	S101 with S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 18:25
S10 3	8	S102 and S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/10 18:25
S10 4	2	("6130383").URPN.	USPAT	OR	ON	2005/06/10 18:37
S10 5	3	("5218759" "5241133" "5635671").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:06
S10 6	2	from adj top	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:07
S10 7	2	"from" adj top	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:07
S10 8	4135446	top upper	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:07
S10 9	72883	S97 near9 S108	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:08
S11 0	344	S109 with S37	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:34

S11 1	104	S109 with S8	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:09
S11 2	25	S111 and S86	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:25
S11 3	77	S110 and S86	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:26
S11 4	52	S113 not S112	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 19:26
S11 5	0	("6777793").URPN.	USPAT	OR	ON	2005/06/10 20:08
S11 6	4	("20030102016" "20040048009" "5185654" "6613979").PN	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/10 20:08
S11 7	952569	gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:16
S11 8	2030	mold adj S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:18
S11 9	65037	runner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:19
S12 0	1006033	S117-S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:19
S12 1	14934	tape adj (substrate base carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:21
S12 2	510	S120 with S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:21
S12 3	2161335	(flexible elast\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:27

S12 4	6088779	(substrate base carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:21
S12 5	169852	S123 near6 S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:22
S12 6	125	S122 and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:25
S12 7	3168090	(encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:25
S12 8	10768	S117 near2 S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:39
S12 9	72353	S128 S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:26
S13 0	25	S129 near8 S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:28
S13 1	28	S129 with S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:29
S13 2	28	S131 and S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:29
S13 3	1867819	gate port	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:39

S13 4	17144	S133 near2 S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:40
S13 5	78463	S134 S119	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 17:41
S13 6	28	S135 with S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:12
S13 7	1664044	communication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:13
S13 8	6482	S137 near4 S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:14
S13 9	0	S138 with S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:14
S14 0	83743	S138 S135	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:14
S14 1	43	S140 same S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/25 18:14
S14 2	15	S141 not S136	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S14 3	65049	runner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02

S14 4	14941	tape adj (substrate base carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:27
S14 5	3168761	(encapsula\$3 encapsulation mold\$3 resin epoxy potting gel.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S14 6	1868394	gate port	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S14 7	17151	S146 near2 S145	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S14 8	78480	S147 S143	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S14 9	28	S148 with S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S15 0	1664716	communication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S15 1	6485	S150 near4 S145	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S15 2	83763	S151 S148	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:02
S15 3	43	S152 same S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:25

S15 4	15	S153 not S149	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:05
S15 5	2161922	(flexible elast\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:45
S15 6	6090180	(substrate base carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:28
S15 7	85354	S155 near2 S156	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:29
S15 8	187	S152 and S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:47
S15 9	24	S158 and S157	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:29
S16 0	557399	etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:30
S16 1	51386	die near (cut\$4 punch\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:30
S16 2	12	S158 and S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:22
S16 3	81	S158 and S160	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 07:31

S16 4	4	09/987532	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 10:29
S16 5	8	("20010003049" "20020089062" "5776798" "5904502" "6245595" "6329220" "6346433" "6358776").PN	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/26 10:45
S16 6	1	("6596561").URPN.	USPAT	OR	ON	2005/07/26 10:45
S16 7	0	("6723583").URPN.	USPAT	OR	ON	2005/07/26 10:53
S16 8	12	("20010003049" "20020089062" "5776798" "5904502" "5914531" "6228684" "6245595" "6287895" "6329220" "6333564" "6346433" "6358776").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/26 10:54
S16 9	0	("6872597").URPN.	USPAT	OR	ON	2005/07/26 10:56
S17 0	14	("20010003049" "20020089062" "5759873" "5776798" "5904502" "5914531" "6228684" "6245595" "6287895" "6329220" "6333564" "6346433" "6358776" "6495379").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/26 10:57
S17 1	5	S170 and S146	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/26 10:57
S17 2	5086991	support\$4 mechanical\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:45
S17 3	5426889	support\$4 mechanical\$3 reinforc\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:47
S17 4	5790	S152 near3 S173	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:47
S17 5	178	S147 near3 S173	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:48
S17 6	2	S144 same S174	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:48

S17 7	6	S144 and S175	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:50
S17 8	282375	tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:51
S17 9	3	S175 same S178	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:52
S18 0	109	S174 same S178	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 12:55
S18 1	10	("5196917").URPN.	USPAT	OR	ON	2005/07/26 13:11
S18 2	22833	S147 S151	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:23
S18 3	1257	S182 near9 S156	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:23
S18 4	8	S183 near9 S160	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:26
S18 5	1	S183 near9 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:29
S18 6	294833	S144 tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:34
S18 7	43	S153 and S186	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:38

S18 8	7202091	(open\$5 hole aperture trench groove cavity concave perforat\$4 depressi\$4 trough)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:40
S18 9	605171	S160 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:40
S19 0	158738	S188 near9 S189	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 13:41
S19 1	5	S187 and S190	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:42
S19 2	1320594	adhes\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:42
S19 3	223416	S192 near8 S145	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:42
S19 4	229237	(elastomer (elastic flexible) adj polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:47
S19 5	1946727	(elastomer (elastic flexible))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:47
S19 6	665	S195 near3 S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:59
S19 7	9	S196 and S147	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:49

S19 8	111	S147 and S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:57
S19 9	5692758	gold:au:titanium ti	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:58
S20 0	10004	S199 near S146	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 17:00
S20 1	2007	S195 same S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:59
S20 2	24	S200 and S201	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 17:00
S20 3	0	S200 and S158	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 17:00
S20 4	16008	S199 with S146	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 17:01
S20 5	5	S158 and S204	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 17:01